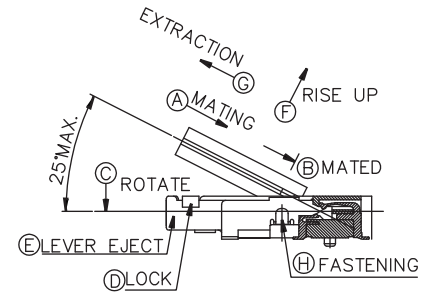
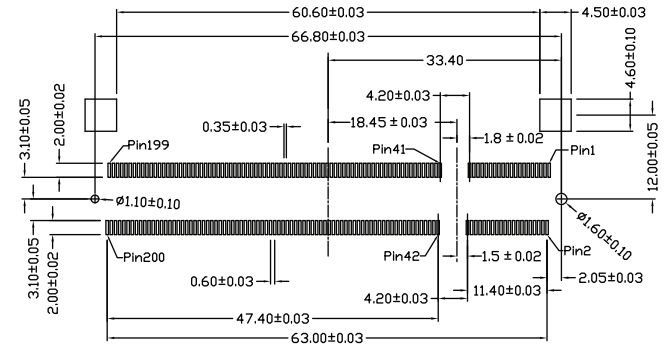
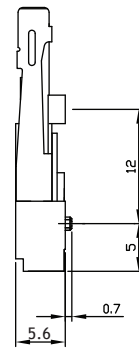
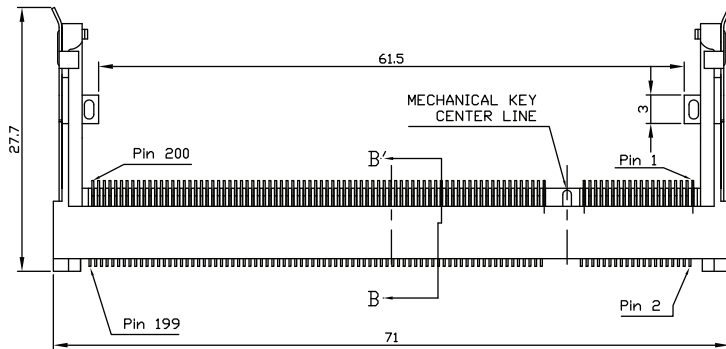


SECTION: B-B



HOW TO MATE AND UNMATE



P.C.B Layout

**HOW TO ORDER:**

**B 0 3 0 - 2 0 0 2 - C 1 X X - Z**

**NUMBER OF CONTACTS:**  
200

**ORIENTATION:**  
1 - Reverse

**PLATING OPTIONS:**  
2 - FULL Au FLASH  
6 - 15µ" Au

**PACKAGING:**  
0 - Tray  
1 - Tape & Reel

**RoHS COMPLIANT**

**KEY TYPE / VOLTAGE OPTION :**  
2 - 2.5 V

**MATERIAL:**

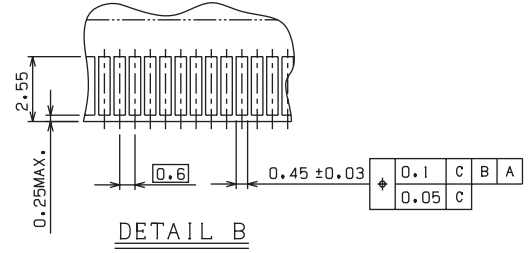
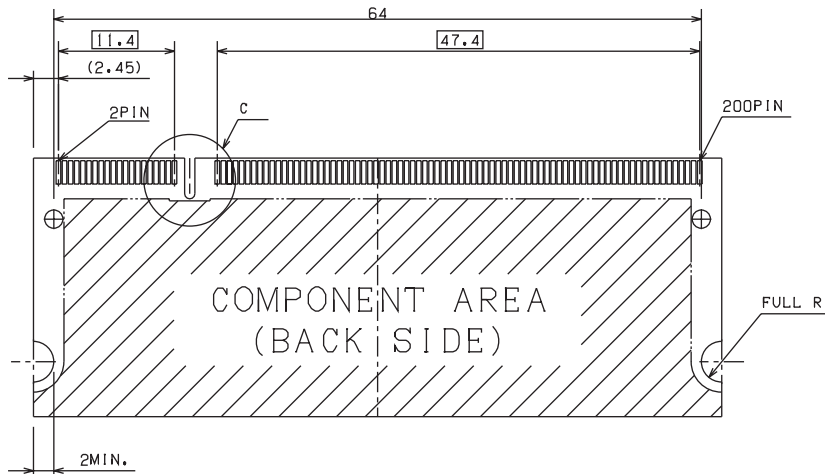
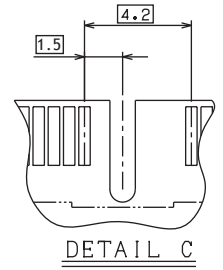
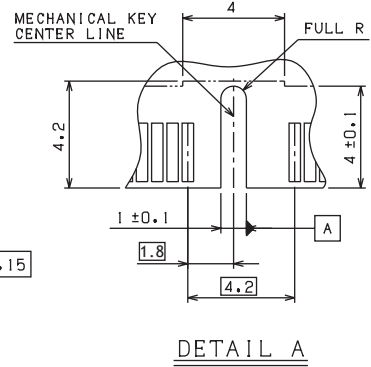
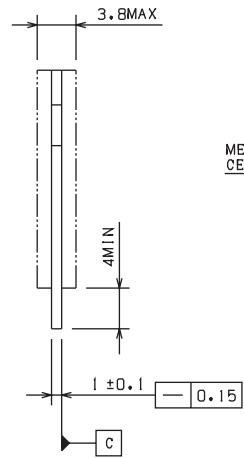
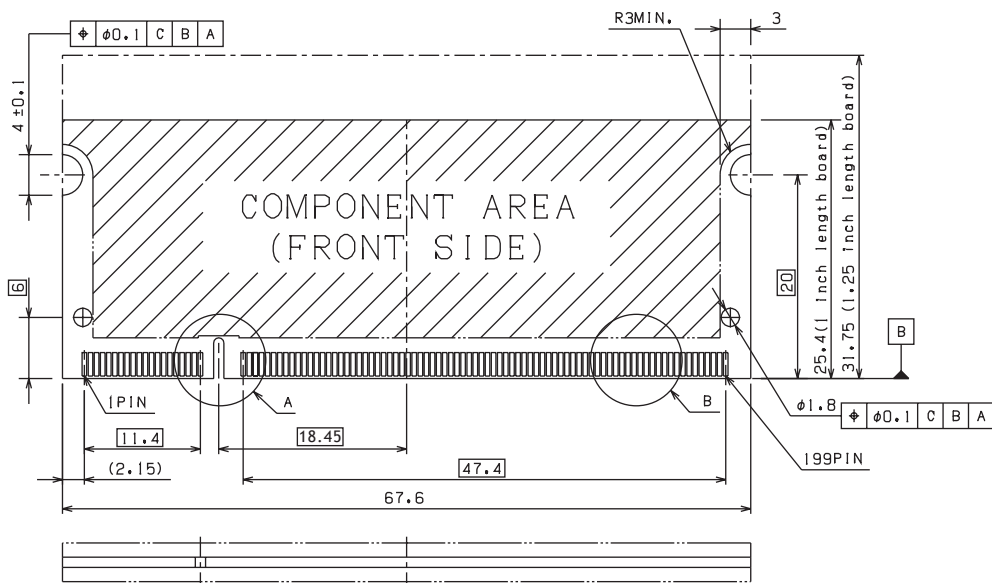
CONTACT PLATING: Gold (selective) on Contact Area  
Nickel Sub Plate (80µ min)  
HOUSING: High Temp Thermo Plastic UL94V-0  
METAL LATCH: Stainless Steel

Rev	Description	Drawn	Checked	Approved	Date
0	Issued	B.S.	S.M.	S.M.	12/01/08
TOL. DEC.	.X +/- 0.38	.XX +/- 0.25	.XXX +/- 0.15	ANGLE +/- 0.3°	UNIT: mm

**SMP TECHNOLOGY, INC.**

DDR Socket, Right Angle, 200 Position, 2.5 Volt, Reverse Orientation,  
Surface Mount, 5.6mm Height

P/N: B030-2002-C1XX-Z



RECOMMENDED MATING  
P.C. BOARD DIM.

Notes: Apply To Sheet 2

1. Tolerances on all dimensions +/- .15 unless otherwise specified.
2. P.C Board thickness applies across tabs and includes plating and metalization.
3. Pad Finish: 0.00076 micro m min over .002 micro m min. Nickel plating.

					<b>SMP TECHNOLOGY, INC.</b>	
					DDR Socket, Right Angle, 200 Position, 2.5 Volt, Reverse Orientation,	
					Surface Mount, 5.6mm Height	
TOL. DEC.	.X +/-	.XX +/-	.XXX +/-	ANGLE +/-	UNIT: mm	P/N: B030-2002-C1XX-Z
						Pg: 2 of 2